

Global 2.5D and 3D IC Packaging Market 2023 by Company, Regions, Type and Application, Forecast to 2029

<https://marketpublishers.com/r/G9B035BB8AFEEN.html>

Date: April 2023

Pages: 111

Price: US\$ 3,480.00 (Single User License)

ID: G9B035BB8AFEEN

Abstracts

According to our (Global Info Research) latest study, the global 2.5D and 3D IC Packaging market size was valued at USD million in 2022 and is forecast to a readjusted size of USD million by 2029 with a CAGR of % during review period. The influence of COVID-19 and the Russia-Ukraine War were considered while estimating market sizes.

In 2.5D structure, two or more active semiconductor chips are placed side-by-side on a silicon interposer for achieving extremely high die-to-die interconnect density. In 3D structure, active chips are integrated by die stacking for shortest interconnect and smallest package footprint.

This report is a detailed and comprehensive analysis for global 2.5D and 3D IC Packaging market. Both quantitative and qualitative analyses are presented by company, by region & country, by Type and by Application. As the market is constantly changing, this report explores the competition, supply and demand trends, as well as key factors that contribute to its changing demands across many markets. Company profiles and product examples of selected competitors, along with market share estimates of some of the selected leaders for the year 2023, are provided.

Key Features:

Global 2.5D and 3D IC Packaging market size and forecasts, in consumption value (\$ Million), 2018-2029

Global 2.5D and 3D IC Packaging market size and forecasts by region and country, in

consumption value (\$ Million), 2018-2029

Global 2.5D and 3D IC Packaging market size and forecasts, by Type and by Application, in consumption value (\$ Million), 2018-2029

Global 2.5D and 3D IC Packaging market shares of main players, in revenue (\$ Million), 2018-2023

The Primary Objectives in This Report Are:

To determine the size of the total market opportunity of global and key countries

To assess the growth potential for 2.5D and 3D IC Packaging

To forecast future growth in each product and end-use market

To assess competitive factors affecting the marketplace

This report profiles key players in the global 2.5D and 3D IC Packaging market based on the following parameters - company overview, production, value, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include ASE Technology, Samsung Electronics, Toshiba, STMicroelectronics and Xilinx, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals, COVID-19 and Russia-Ukraine War Influence.

Market segmentation

2.5D and 3D IC Packaging market is split by Type and by Application. For the period 2018-2029, the growth among segments provide accurate calculations and forecasts for consumption value by Type and by Application. This analysis can help you expand your business by targeting qualified niche markets.

Market segment by Type

2.5D

3D TSV

3D Wafer-level Chip-scale Packaging

Market segment by Application

Consumer Electronics

Medical Devices

Communications and Telecom

Automotive

Other

Market segment by players, this report covers

ASE Technology

Samsung Electronics

Toshiba

STMicroelectronics

Xilinx

Intel

Micron Technology

TSMC

SK Hynix

Amkor Technology

GlobalFoundries

SanDisk (Western Digital)

Synopsys

Invensas

Siliconware Precision Industries

Jiangsu Changjiang Electronics

Powertech Technology

Market segment by regions, regional analysis covers

North America (United States, Canada, and Mexico)

Europe (Germany, France, UK, Russia, Italy, and Rest of Europe)

Asia-Pacific (China, Japan, South Korea, India, Southeast Asia, Australia and Rest of Asia-Pacific)

South America (Brazil, Argentina and Rest of South America)

Middle East & Africa (Turkey, Saudi Arabia, UAE, Rest of Middle East & Africa)

The content of the study subjects, includes a total of 13 chapters:

Chapter 1, to describe 2.5D and 3D IC Packaging product scope, market overview, market estimation caveats and base year.

Chapter 2, to profile the top players of 2.5D and 3D IC Packaging, with revenue, gross margin and global market share of 2.5D and 3D IC Packaging from 2018 to 2023.

Chapter 3, the 2.5D and 3D IC Packaging competitive situation, revenue and global market share of top players are analyzed emphatically by landscape contrast.

Chapter 4 and 5, to segment the market size by Type and application, with consumption value and growth rate by Type, application, from 2018 to 2029.

Chapter 6, 7, 8, 9, and 10, to break the market size data at the country level, with revenue and market share for key countries in the world, from 2018 to 2023. and 2.5D and 3D IC Packaging market forecast, by regions, type and application, with consumption value, from 2024 to 2029.

Chapter 11, market dynamics, drivers, restraints, trends, Porters Five Forces analysis, and Influence of COVID-19 and Russia-Ukraine War

Chapter 12, the key raw materials and key suppliers, and industry chain of 2.5D and 3D IC Packaging.

Chapter 13, to describe 2.5D and 3D IC Packaging research findings and conclusion.

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